

**Amendments to the Claims:**

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Original) A manufacturing method for a device in which some or all of plural elements formed on an original substrate are transferred to a final substrate, and some or all of the transferred elements are used to manufacture the device, comprising:

a first process for providing the plural elements on said original substrate via a separation layer in a condition where terminal sections are exposed to a surface on an opposite side to the separation layer;

a second process for adhering the surface where the terminal sections of said elements to be transferred on the original substrate are exposed, via conductive adhesive, to a surface of the final substrate on a side where conductive sections for conducting with the terminal sections of said elements are provided;

a third process for producing exfoliation in said separation layer between said original substrate and said final substrate; and

a fourth process for separating said original substrate from which the transfer of elements has been completed, from said final substrate.

2. (Currently Amended) The A-manufacturing method for a device according to claim 1, wherein said original substrate is a substrate for forming elements.

3. (Currently Amended) The A-manufacturing method for a device according to claim 1, wherein said conductive adhesive is an anisotropic conductive adhesive.

4. (Currently Amended) The A-manufacturing method for a device according to claim 3, wherein in said second process, a film-like anisotropic conductive adhesive is used as said conductive adhesive, and said film-like adhesive is adhered to the surface on the side where the terminal sections of said element are exposed, or to ~~the position~~ a portion to be

connected to said terminal sections on the surface of said final substrate on the side where the conductive sections are provided.

5. (Currently Amended) The A-manufacturing method for a device according to claim 1, wherein in said second process, said conductive adhesive is provided between each of the elements and the final substrate in liquid form, and then cured.

6. (Currently Amended) The A-manufacturing method for a device according to claim 5, wherein in said second process, said conductive adhesive is selectively arranged by a liquid droplet discharge method.

7. (Currently Amended) The A-manufacturing method for a device according to claim 6, wherein prior to selectively arranging said conductive adhesive by the liquid droplet discharge method, ~~the position where the conductive adhesive for each of the elements~~ elements, or for a portion on the final substrate where the conductive adhesive is arranged ~~is arranged~~, is subjected to a lyophilic treatment, and/or the surroundings of the ~~position-portion of the final substrate~~ where the conductive adhesive is arranged is subjected to a liquid repellent treatment.

8. (Currently Amended) The A-manufacturing method for a device according to claim 6, wherein prior to selectively arranging said conductive adhesive by the liquid droplet discharge method, a partition is formed to enclose the ~~position-conductive section~~ where the conductive adhesive for each of the elements or for the final substrate is arranged, and then, the conductive adhesive is selectively arranged within said partition.

9. (Currently Amended) The A-manufacturing method for a device according to claim 6, wherein prior to selectively arranging said conductive adhesive by the liquid droplet discharge method, a concavity is formed in the final substrate at a junction ~~position-portion of each~~ of the elements with the final substrate, and then the conductive adhesive is selectively arranged in said concavity.

10. (Currently Amended) The A-manufacturing method for a device according to claim 9, wherein ~~each of~~ conductive sections for conducting with the terminal sections of said the corresponding elements are ~~is~~ provided beforehand in said concavity before the conductive adhesive is selectively arranged in said concavity.

11. (Currently Amended) The A-manufacturing method for a device according to claim 1, wherein in a case where there are plural terminal sections of said elements, the conductive adhesive to be formed on each of the terminal sections is formed in a condition of independence for each of the respective terminal sections, and ~~between the independent~~ conductive adhesives on each of the terminal sections are insulated from each other. ~~is insulated.~~

12-17. (Canceled)

18. (Original) A device obtained by a manufacturing method according to claim 1.

19-20. (Canceled)